- 1 1. A display comprising:
- 2 a plurality of substrates;
- a plurality of display elements formed on each
- 4 substrate;
- 5 an integrated circuit block attached to each
- 6 substrate and coupled to at least one of said display
- 7 elements; and
- an integrator to couple said substrates to form a
- 9 tiled display.
- 1 2. The display of claim 1 wherein said display
- 2 element is a light emitting diode.
- 1 3. The display of claim 2 wherein said element is an
- 2 organic light emitting diode.
- 1 4. The display of claim 1 wherein said integrated
- 2 circuit block is a complementary metal oxide semiconductor
- 3 integrated circuit.
- 1 5. The display of claim 1 wherein said substrate
- 2 includes a recess to receive said block.
- 1 6. The display of claim 5 wherein said block and
- 2 said substrate and complementarily shaped.

- 7. The display of claim 1 wherein said block is a driver circuit for said display element.
- 1 8. The display of claim 7 wherein said block is
- 2 located between a plurality of display elements.
- 9. The display of claim 1 wherein said block is
- 2 metallized with said substrate.
- 1 10. The display of claim 1 including a ceramic back
- 2 plane and a front plane including said block.
- 1 11. The display of claim 1 wherein said block is
- 2 formed of a silicon substrate and said substrate is formed
- 3 of glass.
- 1 12. A display comprising:
- 2 a back plane;
- 3 an optical integrator; and
- 4 a front plane between said back plane and said
- 5 optical integrator, said front plane including a plurality
- 6 of emissive display elements formed on said front plane and
- 7 an integrated circuit block secured in said front plane and
- 8 including driver circuits coupled to said display elements
- 9 and to said back plane.

- 1 13. The display of claim 12 wherein said display
- 2 elements are light emitting diodes.
- 1 14. The display of claim 13 wherein said elements are
- 2 organic light emitting diodes.
- 1 15. The display of claim 12 wherein said block is
- 2 formed of a metal oxide semiconductor integrated circuit
- 3 and said front plane is formed of glass.
- 1 16. The display of claim 12 wherein said block is
- 2 deposited in a recess formed in said front plane.
- 1 17. The display of claim 12 wherein said driver
- circuit drives a plurality of adjacent display elements.
- 1 18. A method comprising:
- 2 forming a plurality of light emitting display
- 3 elements on a module;
- 4 forming recesses in said module to receive
- 5 integrated circuit nanoblocks;
- depositing said nanoblocks in said recesses;
- 7 electrically coupling said nanoblocks to said
- 8 display elements; and
- 9 connecting a plurality of modules to form a tiled
- 10 display.

- 1 19. The method of claim 18 including etching a recess
- 2 in said module to receive said integrated circuit
- 3 nanoblock.
- 1 20. The method of claim 18 including forming a
- 2 plurality of nanoblocks by forming a sacrificial layer on a
- 3 silicon substrate, etching said substrate and then finally
- 4 etching said sacrificial layer.
- 1 21. The method of claim 18 including coupling said
- 2 nanoblocks to circuits behind said light emitting display.
- 1 22. The method of claim 18 including coupling said
- 2 nanoblocks to said circuits through bond pads on said
- 3 nanoblocks.